TOSHIBA Photocoupler GaAlAs Ired + Photo IC

# **TLP751**

**Digital Logic Ground Isolation** Line Receiver Microprocessor System Interfaces Switching Power Supply Feedback Control **Analog Signal Isolation** 

The TOSHIBA TLP751 consists of GaAlAs high-output light emitting diode and a high speed detector of one chip photo diodetransistor. This unit is 8-lead DIP.

TLP751 has internal base connection. This base pin should be used for analog application or enable operation. If base pin is open, output signal will be noisy by environmental condition. For this case, TLP750 is suitable.

- Switching speed:  $t_{pHL} = 0.3 \mu s$  (typ.)  $t_{pLH} = 0.5\mu s \text{ (typ.)}(R_L=1.9k\Omega)$
- TTL compatible
- UL recognized: UL1577, file no. E67349
- BSI approved: BS EN60065: 1994,

Certificate no. 7613 BS EN60950: 1992.

Certificate no. 7614

- Isolation voltage: 5000Vrms(min.)
- Option(D4)type

VDE approved: DIN VDE0884 / 06.92,

Certificate no. 68384

Maximum operating insulation voltage: 890VPK

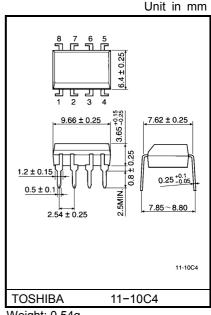
Highest permissible over voltage: 8000VPK

### (Note) When a VDE0884 approved type is needed, please designate the "Option(D4)"

Creepage distance: 6.4mm(min.)

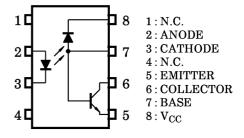
Clearance: 6.4mm(min.)

Insulation thickness: 0.4mm(min.)

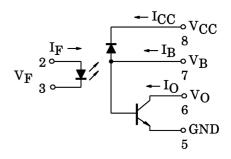


Weight: 0.54g

### Pin Configuration(top view)



#### **Schematic**



### **Maximum Ratings (Ta = 25°C)**

	Characteristic		Symbol	Rating	Unit
TED	Forward current	(Note 1)	lF	25	mA
	Pulse forward current	(Note 2)	I <sub>FP</sub>	50	mA
	Peak transient forward current	(Note 3)	I <sub>FPT</sub>	1	А
	Reverse voltage		V <sub>R</sub>	5	V
	Diode power dissipation	(Note 4)	P <sub>D</sub>	45	mW
Detector	Output current		IO	8	mA
	Peak output current		l <sub>OP</sub>	16	mA
	Output voltage		Vo	-0.5~15	V
	Supply voltage		V <sub>CC</sub>	-0.5~15	V
	Base current		ΙΒ	5	mA
	Output power dissipation	(Note 5)	Po	100	mW
	Emitter-base reverse voltage		V <sub>EB</sub>	5	V
Оре	Operating temperature range		T <sub>opr</sub>	-55~100	°C
Sto	Storage temperature range		T <sub>stg</sub>	-55~125	°C
Lea	Lead solder temperature(10s) (Note 6)		T <sub>sol</sub>	260	°C
	Isolation voltage (AC,1min.,R.H.≤ 60%) (Note 7)		BVS	5000	Vrms

(Note 1) Derate 0.8mA above 70°C

(Note 2) 50% duty cycle,1ms pulse width.

Derate 1.6mA / °C above 70°C

(Note 3) Pulse width  $\leq 1\mu s$ ,300pps.

(Note 4) Derate 0.9mW / °C above 70°C

(Note 5) Derate 2mW / °C above 70°C

(Note 6) Soldering portion of lead : up to 2mm from the body of the device.

(Note 7) Device considered a two terminal device: Pins 1,2,3 and 4 shorted together and pins 5,6,7 and 8 shorted together.

# Electrical Characteristics (Ta = 25°C)

Characteristic		Symbol	Test Condition	Min.	Тур.	Max.	Unit	
LED	Forward voltage	V <sub>F</sub>	I <sub>F</sub> = 16 mA	_	1.65	1.85	V	
	Forward voltage Temperature coefficient	ΔV <sub>F</sub> / ΔTa	I <sub>F</sub> = 16 mA	_	-2	_	mV / °C	
	Reverse current	$I_{R}$	V <sub>R</sub> = 5 V	_	_	10	μΑ	
	Capacitance between terminal	СТ	V <sub>F</sub> = 0, f = 1 MHz	_	45	_	pF	
Detector	High level output current	I <sub>OH</sub> (1)	$I_F = 0 \text{ mA}, V_{CC} = V_O = 5.5 \text{ V}$	_	3	500	nA	
		I <sub>OH</sub> (2)	I <sub>F</sub> = 0 mA, V <sub>CC</sub> = V <sub>O</sub> = 15 V	_	_	5		
		Іон	I <sub>F</sub> = 0 mA, V <sub>CC</sub> = V <sub>O</sub> = 15 V	_	_	50	μА	
			Ta = 70°C					
	High level supply voltage	I <sub>CCH</sub>	I <sub>F</sub> = 0 mA, V <sub>CC</sub> = 15 V	_	0.01	1	μΑ	
Coupled	Current transfer ratio	I <sub>O</sub> / I <sub>F</sub>	I <sub>F</sub> = 16 mA, V <sub>CC</sub> = 4.5 V	10	30	_	%	
			V <sub>O</sub> = 0.4 V	10				
	Low level output voltage	V <sub>OL</sub>	I <sub>F</sub> = 16 mA, V <sub>CC</sub> = 4.5 V		_	0.4	V	
			I <sub>O</sub> = 1.1 mA	_				
	resistance(input-output)	R <sub>S</sub>	R.H. ≤ 60%, V <sub>S</sub> = 500 V <sub>DC</sub> (Note7)	1×10 <sup>12</sup>	10 <sup>14</sup>	_	Ω	
	Capacitance (input-output)	C <sub>S</sub>	V <sub>S</sub> = 0, f = 1 MHz (Note7)	_	0.8	_	pF	

# Switching Characteristics (Ta = 25°C, $V_{CC} = 5V$ )

Characteristic		Symbol	Test Cir- cuit	Test Condition	Min.	Тур.	Max.	Unit
Propagation delay time (H→L)		t <sub>pHL</sub>	1	$I_F = 0 \rightarrow 16$ mA, $V_{CC} = 5$ V, $R_L = 4.1$ kΩ	-	0.2	_	μs
Propagation delay time (L→H)		t <sub>pLH</sub>		$I_F$ = 16→0mA $V_{CC}$ = 5V, $R_L$ = 4.1 kΩ	_	1.0	_	μs
Common mode transient immunity at logic high output	(Note 8)	CM <sub>H</sub>		$I_F = 0 \text{ mA}, V_{CM} = 200 V_{p-p}$ $R_L = 4.1 \text{ k}\Omega$	1	400	ı	V / µs
Common mode transient immunity at logic low output	(Note 8)	CML	2	$I_F = 16 \text{ mA}$ $V_{CM} = 200 V_{p-p}$ $R_L = 4.1 \text{ k}\Omega$	_	-1000	_	V / µs

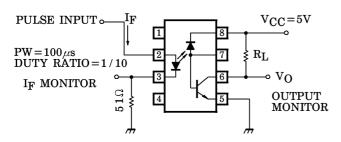
3 2002-09-25

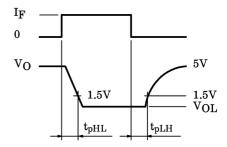
(Note 8) CM<sub>L</sub> is the maximum rate of fall of the common mode voltage that can be sustained with the output voltage in the logic low state( $V_Q < 0.8V$ ).

 $CM_H$  is the maximum rate of rise of the common mode voltage that can be sustained with the output voltage in the logic high state( $V_Q > 2.0V$ ).

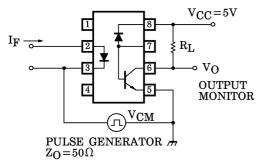
(Note 9) Maximum electrostatic discharge voltage for any pins: 100V (C = 200pF, R = 0).

### **Test Circuit 1: Switching Time Test Circuit**

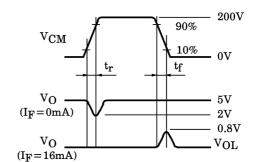


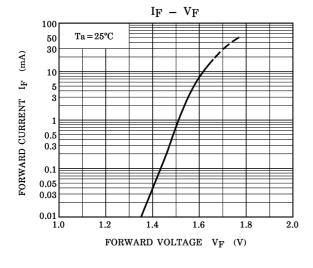


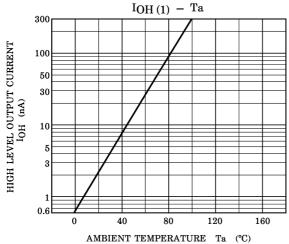
### **Test Circuit 2: Common Mode Noise Immunity Test Circuit**

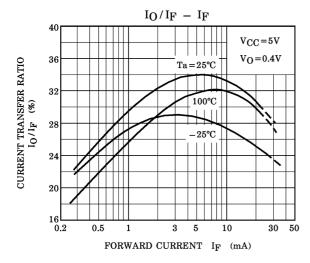


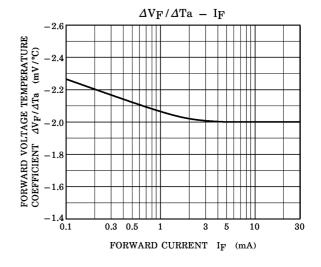
$$\text{CM}_H = \frac{160 \, \text{(V)}}{t_r \, (\mu \text{s})}$$
 ,  $\text{CM}_L = \frac{160 \, \text{(V)}}{t_f \, (\mu \text{s})}$ 

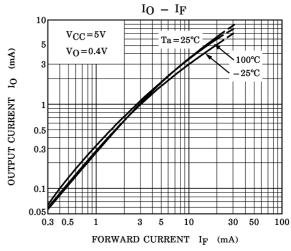


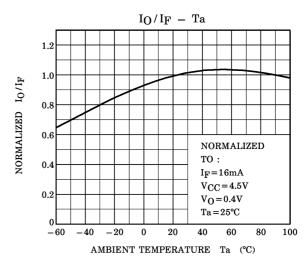




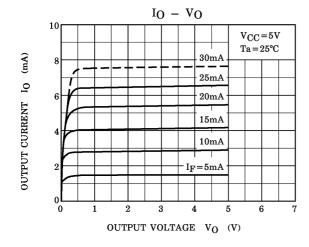


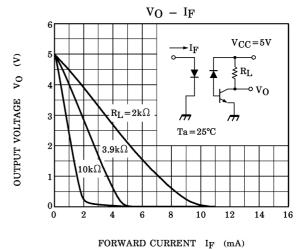






5





6 2002-09-25

#### RESTRICTIONS ON PRODUCT USE

000707EBC

- TOSHIBA is continually working to improve the quality and reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing TOSHIBA products, to comply with the standards of safety in making a safe design for the entire system, and to avoid situations in which a malfunction or failure of such TOSHIBA products could cause loss of human life, bodily injury or damage to property. In developing your designs, please ensure that TOSHIBA products are used within specified operating ranges as set forth in the most recent TOSHIBA products specifications. Also, please keep in mind the precautions and conditions set forth in the "Handling Guide for Semiconductor Devices," or "TOSHIBA Semiconductor Reliability Handbook" etc..
- The TOSHIBA products listed in this document are intended for usage in general electronics applications (computer, personal equipment, office equipment, measuring equipment, industrial robotics, domestic appliances, etc.). These TOSHIBA products are neither intended nor warranted for usage in equipment that requires extraordinarily high quality and/or reliability or a malfunction or failure of which may cause loss of human life or bodily injury ("Unintended Usage"). Unintended Usage include atomic energy control instruments, airplane or spaceship instruments, transportation instruments, traffic signal instruments, combustion control instruments, medical instruments, all types of safety devices, etc.. Unintended Usage of TOSHIBA products listed in this document shall be made at the customer's own risk.
- Gallium arsenide (GaAs) is a substance used in the products described in this document. GaAs dust and fumes
  are toxic. Do not break, cut or pulverize the product, or use chemicals to dissolve them. When disposing of the
  products, follow the appropriate regulations. Do not dispose of the products with other industrial waste or with
  domestic garbage.
- The products described in this document are subject to the foreign exchange and foreign trade laws.
- The information contained herein is presented only as a guide for the applications of our products. No
  responsibility is assumed by TOSHIBA CORPORATION for any infringements of intellectual property or other
  rights of the third parties which may result from its use. No license is granted by implication or otherwise under
  any intellectual property or other rights of TOSHIBA CORPORATION or others.
- The information contained herein is subject to change without notice.